12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20121028001
Qualification of Aizu Facility as an additional FAB source for select ADS1282IPWxx devices in the 50HPA07 Process
Change Notification / Sample Request

Date: 10/31/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20121028001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS1282IPW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20121028001	**PCN Date:**	10/31/2012
Title:	Qualification of Aizu Facility as an additional FAB source for select ADS1282IPWxx devices in the 50HPA07 Process		

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	01/31/2013	**Estimated Sample Availability:**	Date provided at sample request.		

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the qualification of its AIZU fabrication facility as an additional wafer FAB source for the select ADS1282IPWxx devices in the 50HPA07 Process. The affected devices are listed in "Product Affected" section.

Currently Qualified Sites, Process	**Additional Site, Process**
DM5, 50HPA07 Process	**AIZU, 50HPA07 Process**

The 50HPA07 process was previously qualified in Aizu in June 2011. Qualification details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
DP1DM5	DM5	USA

New

Chip Site	Chip site code (20L)	Chip country code (21L)
AIZU	**CU2**	**JPN**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
G4

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

ADS1282IPW	ADS1282IPW-1G4	ADS1282IPWR	ADS1282IPWR-1G4
ADS1282IPW-1	ADS1282IPWG4	ADS1282IPWR-1	ADS1282IPWRG4

Qualification Data: Approved 6/3/2011

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TMP431BDGK

Wafer Fab Site:	AIZU	Metallization:	0.2kÅTi/0.425kÅTiN/5.4kÅAlCu0.5%/0.275kÅTiN
Wafer Fab Process:	50HPA07	Wafer diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Life Test	150C (300 Hrs)	77/0	77/0	-
Electrical Characterization	Over temp	Pass	Pass	-
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	-
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	-
**T/C -65C/150C	-65C/+150C (500 Cycles)	77/0	77/0	-
ESD HBM	Per JEDEC	3/0	-	-
ESD CDM	Per JEDEC	3/0	-	-
Wafer level Reliability	Per Site Specification	Pass	Pass	Pass
Latch-up	(per JESD78)	6/0	-	-
Manufacturability	(per mfg. Site specification)	Pass	Pass	-

** Preconditioning sequence: level 2 @ 260C

Qual Vehicle 2: OPA2333AIDGK

Wafer Fab Site:	AIZU	Metallization:	Ti/TiN/AlCu .5
Wafer Fab Process:	50HPA07	Wafer diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Life Test	150C (300 Hrs)	77/0	-	-
Electrical Characterization	Over temp	Pass	-	-
**Biased HAST	130C/85%RH (96 Hrs)	80/0	-	-
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	80/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cycles)	80/0	-	-
ESD HBM	Per JEDEC	3/0	-	-
ESD CDM	Per JEDEC	3/0	-	-
Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	-	-
Latch-up	(per JESD78)	6/0	-	-
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	-	-
Wafer Level Reliability	(per mfg. Site specification)	Pass		

** Preconditioning sequence: level 2 @ 260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com